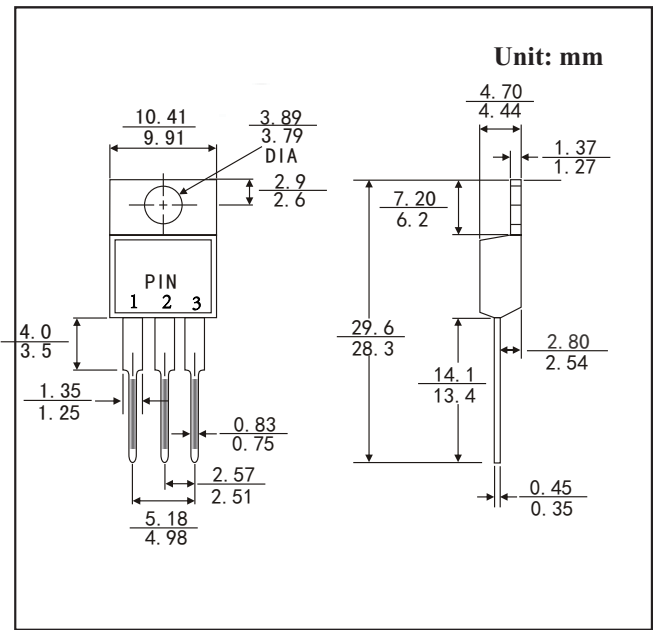
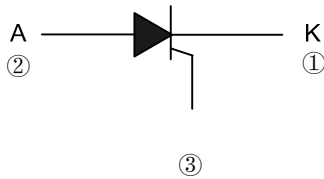


TO-220AB Silicon Controlled Rectifier

Description

Passivated thyristors in a plastic envelope, intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

Symbol



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

PARAMETER	SYMBOL	RATINGS	UNIT
Repetitive Peak Off-State Voltages	V_{DRM}, V_{RRM}	500 (Note 2)	V
		650 (Note 2)	
		800	
Average On-State Current (half sine wave; $T_{mb} \leq 109^\circ\text{C}$)	$I_{T(AV)}$	7.5	A
RMS on-State Current (all conduction angles)	$I_{T(RMS)}$	12	A
Non-Repetitive Peak On-State Current (half sine wave; $T_J = 25^\circ\text{C}$ prior to surge)	I_{TSM}	100	A
		110	
I^2t for Fusing ($t = 10$ ms)	I^2t	50	A^2s
Repetitive Rate of Rise of On-State Current After Triggering ($I_{TM} = 20$ A; $I_G = 50$ mA; $dI_G/dt = 50$ mA/ μs)	dI_T/dt	50	A/ μs
Peak Gate Current	I_{GM}	2	A
Peak Gate Voltage	V_{GM}	5	V
Peak Reverse Gate Voltage	V_{RGM}	5	V
Peak Gate Power	P_{GM}	5	W
Average Gate Power (Over any 20 ms period)	$P_{G(AV)}$	0.5	W
Operating Junction Temperature	T_J	125	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 ~ 150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15A/ μs .

THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Mounting Base	θ_{JMb}	1.3	K/W
Junction to Ambient	θ_{JA}	60	K/W

STATIC CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Gate Trigger Current	I_{GT}	$V_D = 12\text{ V}, I_T = 0.1\text{ A}$			10	mA
Latching Current	I_L	$V_D = 12\text{ V}, I_{GT} = 0.1\text{ A}$			40	mA
Holding Current	I_H	$V_D = 12\text{ V}, I_{GT} = 0.1\text{ A}$			30	mA
On-State Voltage	V_T	$I_T = 23\text{ A}$			1.75	V
Gate Trigger Voltage	V_{GT}	$V_D = 12\text{ V}, I_T = 0.1\text{ A}$ $V_D = V_{DRM(max)}, I_T = 0.1\text{ A}, T_J = 125^\circ\text{C}$	0.35		1.5	
Off-State Leakage Current	I_D, I_R	$V_D = V_{DRM(max)}, V_R = V_{RRM(max)}, T_J = 125^\circ\text{C}$			0.5	mA

DYNAMIC CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS		MIN	MAX	UNIT	
Critical Rate of Rise of Off-State Voltage	dV _D /dt	V _{DM} = 67% V _{DRM(max)} , T _J = 125 °C, exponential waveform;	Gate open circuit	50	130		V/μs
			R _{GK} = 100Ω	200	1000		
Gate Controlled Turn-on Time	t _{GT}	I _{TM} = 40 A, V _D = V _{DRM(max)} , I _G = 0.1 A, dI _G /dt = 5 A/μs			2		μs
Circuit Commutated Turn-off time	t _Q	V _D = 67% V _{DRM(max)} , T _J = 125°C; I _{TM} = 20 A, V _R = 25 V, dI _{TM} /dt = 30 A/μs, dV _D /dt = 50 V/μs, R _{GK} = 100 Ω			70		μs

TYPICAL CHARACTERISTICS

Fig 1. Maximum On-State Dissipation,

P_{tot} , Versus Average On-State Current, $I_{T(AV)}$,
Where $a = \text{form factor} = I_{T(RMS)}/I_{T(AV)}$

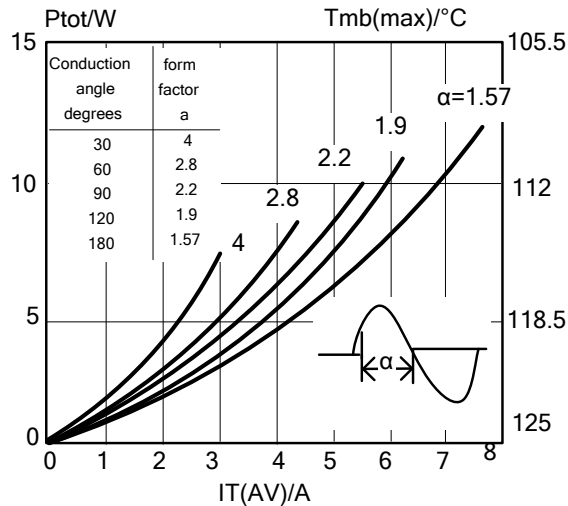


Fig 2. Maximum Permissible Non-Repetitive Peak On-State Current I_{TSM} , Versus Pulse Width t_p for Sinusoidal Currents, $t_p \leq 10\text{ms}$ I_{TSM}/A

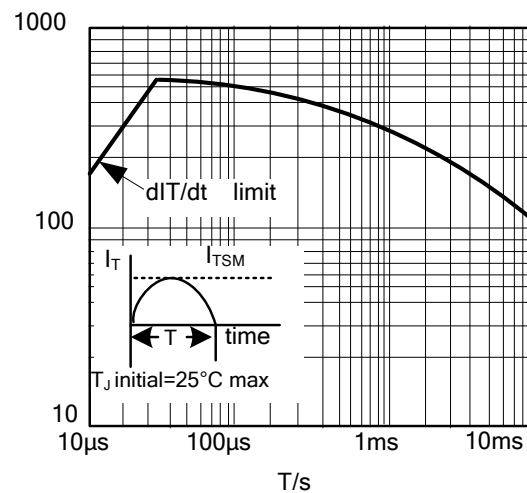


Fig 3. Maximum Permissible Rms Current $I_T(RMS)$, Versus Mounting Base Temperature T_{mb}

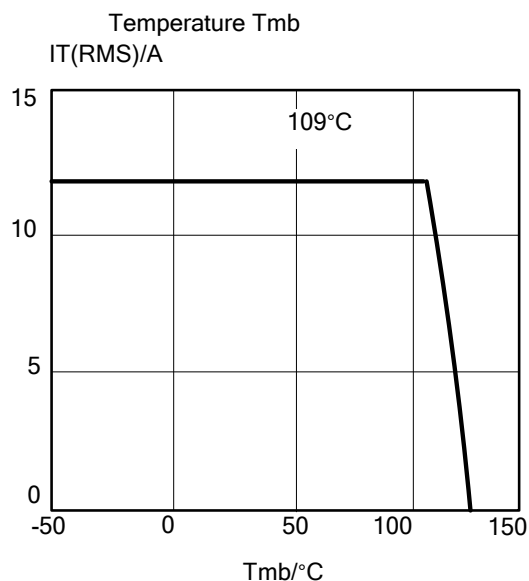


Fig 4. Maximum Permissible Non-Repetitive Peak On-State Current I_{TSM} , Versus Number Of Cycles, For Sinusoidal Currents, $f=50HZ$

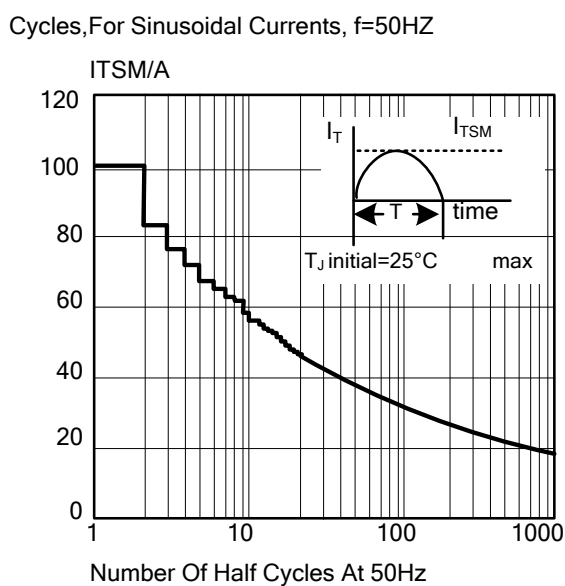


Fig 5. Maximum Permissible Repetitive Rms On-State Current $I_T(RMS)$, Versus Surge Duration, For Sinusoidal Currents, $f=50HZ$; $T_{mb} \leq 109^{\circ}C$

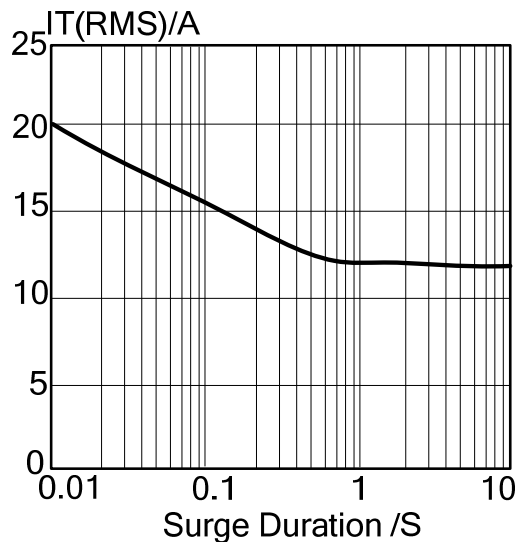
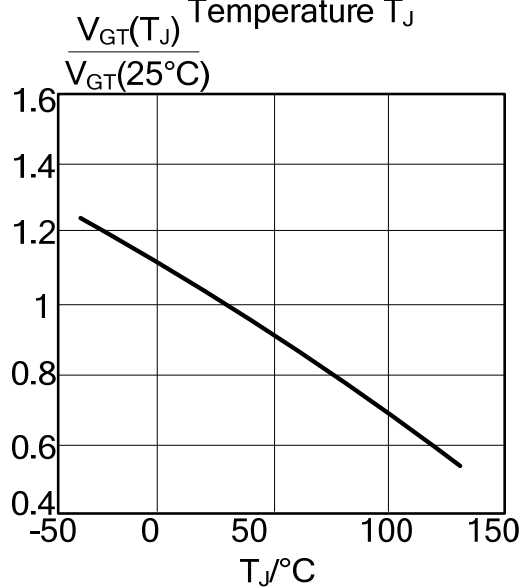


Fig 6. Normalised Gate Trigger Voltage $V_{GT}(T_J)/V_{GT}(25^{\circ}C)$, Versus Junction Temperature T_J



TYPICAL CHARACTERISTICS(Cont.)

Fig 7. Normalised Gate Trigger Current $I_{GT}(T_J)/I_{GT}(25^\circ\text{C})$, Versus Junction Temperature T_J

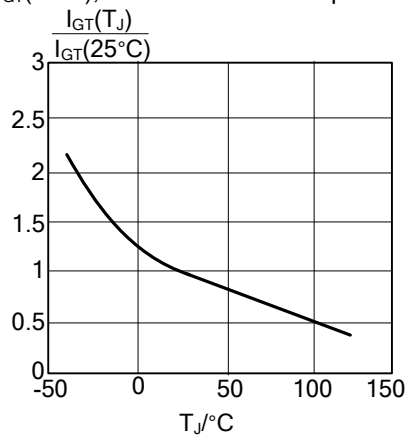


Fig 8. Normalised Latching Current $I_L(T_J)/I_L(25^\circ\text{C})$, Versus Junction Temperature T_J

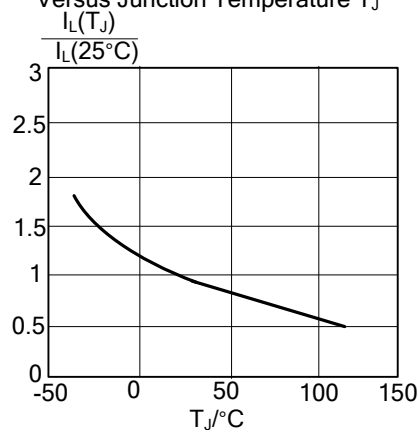


Fig 9. Normalised Holding Current $I_H(T_J)/I_H(25^\circ\text{C})$, Versus Junction Temperature T_J

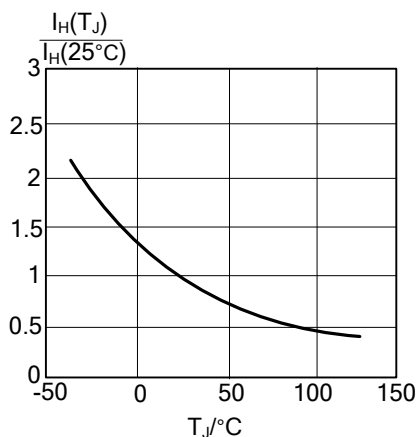


Fig 10. Typical and Maximum On-State Characteristic

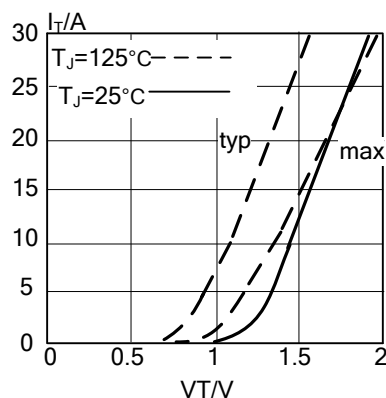


Fig 11. Transient Thermal Impedance Z_{thj-mb} , Versus Pulse Width t_p

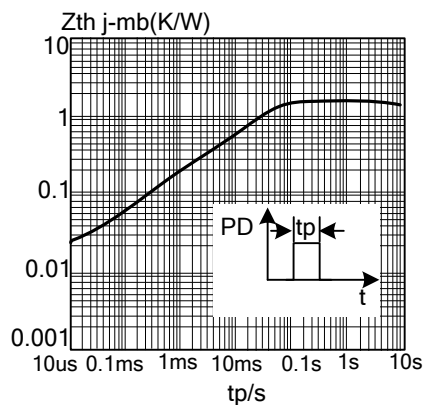


Fig 12. Typical, Critical Rate Of Rise Of Off-State Voltage, dV_D/dt Versus Junction Temperature T_J

